

May 2013

FSA2257 Low R_{ON}, Low-Voltage Dual SPDT Bi-Directional Analog Switch

Features

- Maximum 1.15 Ω On Resistance (R_{ON}) at 4.5 V V_{CC}
- 0.3 Ω Maximum R_{ON} Flatness at +5 V V_{CC}
- Space-Saving MicroPak™
- Broad V_{CC} Operating Range: 1.65 V to 5.50 V
- Fast Turn-On and Turn-Off Time
- Break-Before-Make Enable Circuitry
- Over-Voltage Tolerant TTL-Compatible Control Input

Applications

- Cell Phone
- PDA
- Mobile Devices

Description

The FSA2257 is a high-performance bi-directional dual Single-Pole/Double-Throw (SPDT) analog switch. This switch can be configured as either a multiplexer or a demultiplexer by select pins. The device features ultra-low R_{ON} of 1.3 Ω maximum at 4.5 V V_{CC} and operates over the wide V_{CC} range of 1.65 V to 5.50 V. The device is fabricated with submicron CMOS technology to achieve fast switching speeds and is designed for break-beforemake operation. The select input is TTL-level compatible.

Ordering Information

Part Number	Package Number	Top Mark	Package Description	Packing Method
FSA2257L10X	MAC10A	EP	10-Lead MicroPak™, 1.6 x 2.1 mm	5000 Units Tape and Reel
FSA2257MTCX	MCT14	FSA2257	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4 mm Wide	2500 Units Tape and Reel
FSA2257MUX	MUA10A	FSA 2257	10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0 mm	4000 Units Tape and Reel

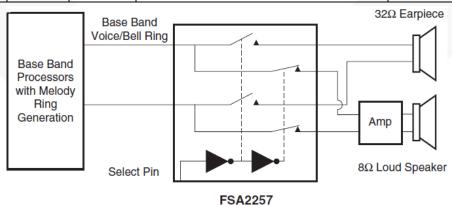
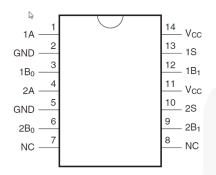


Figure 1. Block Diagram

Pin Configurations



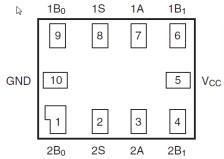
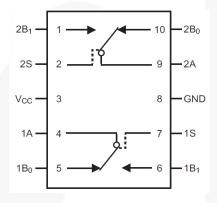


Figure 2. Pin Assignments for TSSOP (Top View)





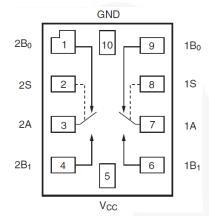


Figure 4. Pin Assignments for MSOP (Top View)

Figure 5. Analog Symbols (Top Through View)

Pin Definitions

Pin# TSSOP	Pin# MicroPak™	Pin # MSOP	Name	Description		
1	7	4	1A	Data Ports		
2,5	10	8	GND	Ground		
3	9	5	1B ₀	Data Ports		
4	3	9	2A	Data Ports		
6	1	10	2B ₀	Data Ports		
7,8			NC	No Connect		
9	4	1	2B ₁	Data Ports		
10	2	2	28	Control Inputs		
11,14	5	3	Vcc	Power Supply		
12	6	6	1B ₁	Data Ports		
13	8	7	1S	Control Inputs		

Truth Table

Control Input (S)	Function			
Low Logic Level	B ₀ connected to A			
High Logic Level	B ₁ connected to A			

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Paramet	Min.	Max.	Unit	
V _{CC}	Supply Voltage		-0.5	6.0	V
V _{SW}	DC Switch Voltage ⁽¹⁾		-0.5	V _{CC} + 0.5	V
V _{IN}	DC Input Voltage ⁽¹⁾		-0.5	6.0	V
	Input Diode Current		-50		
I_{IK}	Switch Current			200	mA
	Peak Switch Current (Pulsed at 1 ms duration, <10% duty cy			400	
T _{STG}	Storage Temperature Range		-65	+150	°C
TJ	Maximum Junction Temperature			+150	°C
TL	Lead Temperature (Soldering, 10 sec	conds)		+260	°C
LCD	Electrostatic Discharge Canability	Human Body Model, JESD22-A114		8000	V
ESD	Electrostatic Discharge Capability	Charged Device Model, JESD22-C101		2000	V

Note

1. Input and output negative ratings may be exceeded if input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V _{CC}	Supply Voltage	1.65	5.50	V
V_{CNTRL}	Control Input Voltage ⁽²⁾	0	V _{CC}	V
V _{SW}	Switch Input Voltage	0	V _{CC}	V
T _A	Operating Temperature	-40	+85	°C

Note:

2. Unused control input must be held HIGH or LOW and it must not float.

DC Electrical Characteristics

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V _{cc} (V)	T _A =+25°C			T _A =-40°C to +85°C		Unit	
•				Min.	Тур.	Max.	Min.	Max.	1	
			1.8 to 2.7				1.0			
V_{IH}	Input Voltage High		2.7 to 3.6				2.0		V	
			4.5 to 5.5				2.4			
			1.8 to 2.7					0.4		
V_{IL}	Input Voltage Low		2.7 to 3.6					0.6	V	
			4.5 to 5.5					0.8		
	Control Input		2.7 to 3.6				-1.0	1.0		
I _{IN}	Leakage	V _{IN} =0 V to V _{CC}	4.5 to 5.5				-1.0	1.0	μΑ	
I _{NO(OFF)} , I _{NC(OFF)}	Off Leakage Current of Port B ₀ and B ₁	A=1 V, 4.5 V, B ₀ or B ₁ =1 V, 4.5 V	5.5	-2	\	2	-20	20	nA	
I _{A(ON)}	On Leakage Current of Port A	A=1 V, 4.5V, B ₀ or B ₁ =1 V,4.5 V or Floating	5.5	-4		2	-40	40	nA	
		I _{OUT} =100 mA,	1.8		4.6				Ω	
	Switch On Resistance	B ₀ or B ₁ =1.5 V	2.7		2.6	4.0		4.3		
Ron	R _{ON} MicroPak ⁽³⁾ Switch On	I _{OUT} =100 mA, B ₀ or B ₁ =3.5 V	4.5		0.95	1.15		1.30		
TON		I _{OUT} =100 mA, B ₀ or B ₁ =1.5 V	2.7		2.8			4.5	32	
	Resistance MSOP/TSSOP ⁽³⁾	I _{OUT} =100 mA, B ₀ or B ₁ =3.5 V	4.5		1.5			2.3		
A.D.	On Resistance Matching Between Channels MicroPak (4)	I _{OUT} =100 mA,	4.5		0.06	0.12		0.15	0	
ΔR_{ON}	On Resistance Matching Between Channels MSOP / TSSOP ⁽⁴⁾	B ₀ or B ₁ =3.5 V	4.5		0.7			0.3	Ω	
\ \	\\.	I _{OUT} =100 mA, B ₀ or	1.8		3.0					
_	On Resistance	B _I =0 V, 0.75 V,1.5 V	2.7		1.4					
R _{FLAT(ON)} Flatnes	Flatness ⁽⁵⁾	I _{OUT} =100 mA, B ₀ or B _I =0 V, 1 V, 2 V	4.5		0.2	0.3		0.4	Ω	
1-	Quiescent Supply	V _{IN} =0 V or V _{CC} ,	3.6		0.1	0.5		1.0		
I _{CC}	Current	I _{OUT} =0 V	5.5		0.1	0.5		1.0	μΑ	

Notes:

- On resistance is determined by the voltage drop between A and B pins at the indicated current through the
- 4. \(\Delta R_{ON} = R_{ONmin} \) measured at identical V_{CC}, temperature, and voltage.
 5. Flatness is defined as the difference between the maximum and minimum value of on resistance over the specified range of conditions.

AC Electrical Characteristics

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V _{cc} (V)	T _A =+25°C			T _A =-40°C to +85°C		Unit	Figure
				Min.	Тур.	Max.	Min.	Max.		
		B ₀ or B ₁ =1.5 V,	1.8 to 2.7		75					
t _{ON}	Turn-On	R _L =50 Ω , C _L =35 pF	2.7 to 3.6	12		50		60	ns	Figure 6
ION	Time	B_0 or B_1 =3.0 V, R_L =50 Ω, C_L =35 pF	4.5 to 5.5			35		40	110	i iguio o
		B ₀ or B ₁ =1.5 V,	1.8 to 2.7		20					
t _{OFF}	Turn-Off	$R_L=50 \Omega$, $C_L=35 pF$	2.7 to 3.6			20		30	ns	Figure 6
TOFF	Time	B_0 or B_1 =3.0 V, R_L =50 Ω, C_L =35 pF	4.5 to 5.5			15		20	113	i iguic o
	Break-	B_0 or B_1 =1.5 V, R_L =50 Ω, C_L =35 pF	2.7 to 3.6				1			
t _{BBM}	Before-Make Time	: B ₀ or B ₄ =3.0 V	4.5 to 5.5		20		1		ns	Figure 7
Q	Charge	C _L =1.0 nF, V _{GEN} =0 V,	2.7 to 3.6		20				рС	Figure 9
Q	Injection	R _{GEN} =0 Ω	4.5 to 5.5		10				ρС	rigule 9
OIRR	Off Isolation	f =1 MHz, R_L =50 $Ω$	2.7 to 3.6		-70				dB	Figure 8
OIKK	On isolation	= 1 WII 12,	4.5 to 5.5		-70				uБ	rigule 8
			2.7 to 3.6		-75					
Xtalk	Xtalk Crosstalk	f=1 MHz, R_L =50 Ω	4.5 to 5.5		-75				dB	Figure 8
DW	-3 db	B 50.0	2.7 to 3.6		200				N 41 1-	Figure
BW	Bandwidth	R _L =50 Ω	4.5 to 5.5		200				MHz	11
THD	Total Harmon	R _L =600 Ω, V _{IN} =0.5 V _{PP}	2.7 to 3.6		0.002				%	Figure
1110	Distortion	f=20 Hz to 20 kHz	4.5 to 5.5		0.002				70	12

Capacitance

Symbol	Parameter	Conditions	V _{cc} (V)	T _A =+25°C			Unit	Figure	
				Min.	Тур.	Max.		14.)	
C _{IN}	Control Pin Input Capacitance	f=1 MHz	0		3.5		pF	Figure 10	
C _{OFF}	B Port Off Capacitance	f=1 MHz	4.5		12.0		pF	Figure 10	
C _{ON}	A Port On Capacitance	f=1 MHz	4.5		40.0		pF	Figure 10	

AC Loadings and Waveforms

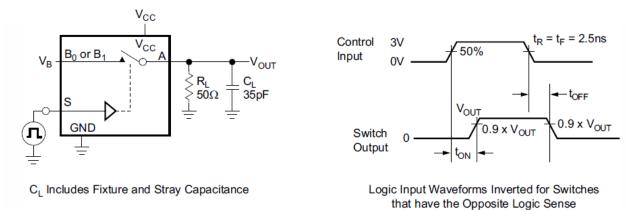
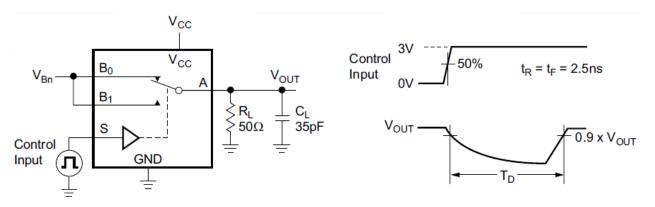


Figure 6. Turn On / Off Timing



C_L Includes Fixture and Stray Capacitance

Figure 7. Break Before Make Timing

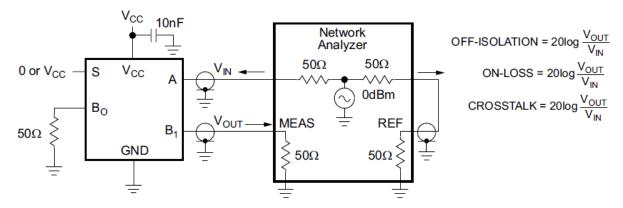


Figure 8. Off Isolation and Crosstalk

AC Loadings and Waveforms (Continued)

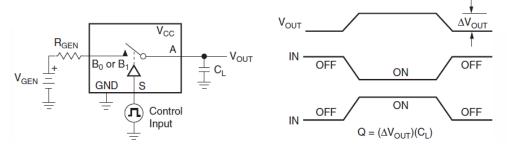


Figure 9. Charge Injection

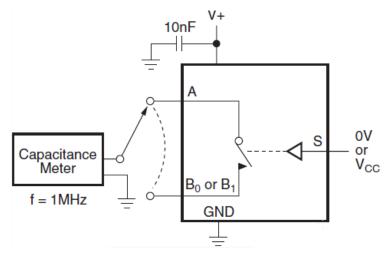


Figure 10. On / Off Capacitance Measurement Setup

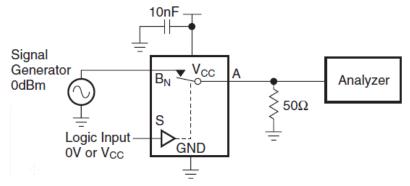


Figure 11. Bandwidth

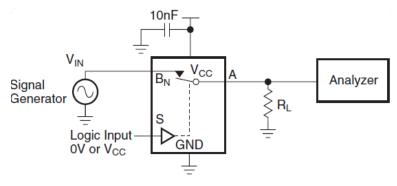
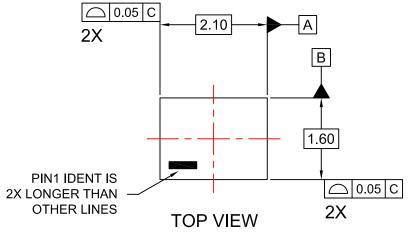
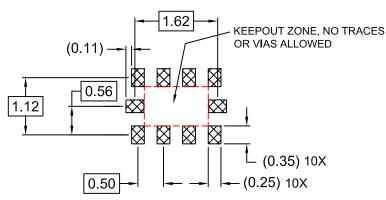


Figure 12. Harmonic Distortion

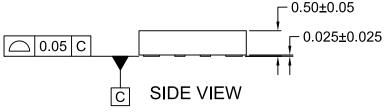


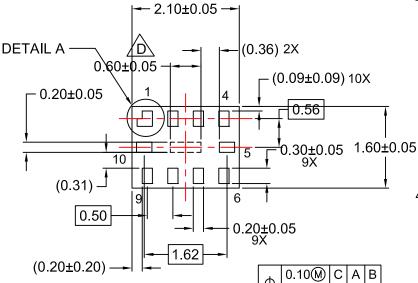




RECOMMENDED LAND PATTERN

 (0.10 ± 0.10)





 $|\Psi|_{0.05 \textcircled{M}}|_{ extsf{C}}|$ ALL FEATURES

0.15±0.05

DETAIL A 2X SCALE

NOTES:

A. PACKAGE CONFORMS TO JEDEC REGISTRATION MO-255, VARIATION UABD.

0.20±0.05

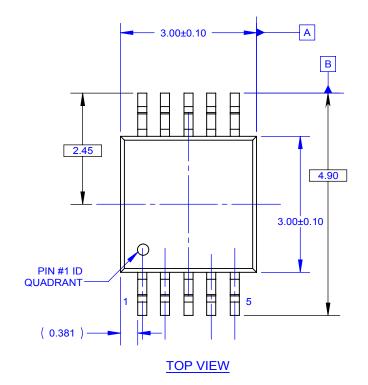
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- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. PRESENCE OF CENTER PAD IS PACKAGE SUPPLIER DEPENDENT. IF PRESENT IT IS NOT INTENDED TO BE SOLDERED AND HAS A BLACK OXIDE FINISH.
 - E. DRAWING FILENAME: MKT-MAC10Arev6.
 - F. DIMENSIONS WITHIN () ARE UNCONTROLLED

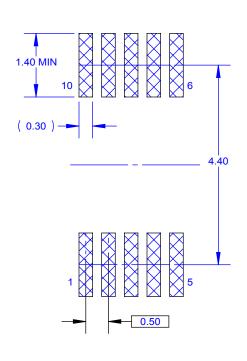


BOTTOM VIEW

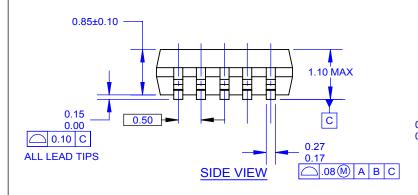
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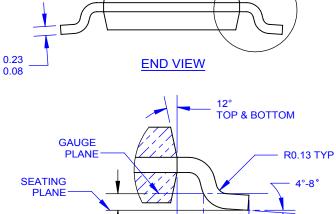
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3	* REVERT LEAD WIDTH TO 0.27MAX.	24SEP2009	KHLEE/FSSZ					





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NOTES: UNLESS OTHERWISE SPECIFIED

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- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS,
 MOLD FLASH AND TIE BAR EXTRUSIONS.
 D. DIMENSIONS AND TOLERANCES AS PER ASME
- Y14.5-1994.
- E. LAND PATTERN AS PER IPC7351#SOP50P490X110-10AN
- F. FILE NAME: MKT-MUA10AREV3

DETAIL A SCALE 20:1

0.80 0.40

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APPROVALS	DATE					
BOBOY MALDO	24SEP09			RCHILE		
CHECKED: KH LEE						
APPROVED: BY HUANG	10LD, MSOP, JEDEC					
APPROVED: HOWARD ALLEN		MO-187, 3.0MM WIDE				
PROJECTION [MM] INCH		SCALE SIZE DRAWING NUMBER 1:1 N/A MKT-MUA10A			JA10A	REV 3
		FORMERLY: N/A			SHEET: 1	OF 1





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